



# IEEE EMC Society Technical Committee 4 – EMI Control

http://emcs.org/committees/tc04/index.html
Meeting Minutes

Place: Shaw Convention Center, Ottawa Canada

Date: 27 July 2016

#### 1 Welcome & Introductions

The meeting called to order at 1203 by Mr. John Kraemer, TC-4 Chair. The Chair briefly described the requirements for membership vs observer, for the sake of correctly signing the attendance sheet. Attendees introduced themselves. The attendance sheet was passed around for signatures; it is attached (Appendix A).

## 2 Review of Draft Agenda

Reviewed and approved without changes

# 3 Approval of the Aug 19, 2015 Meeting Minutes http://www.emcs.org/committees/tc04/reports/tc4minutes2015 08.pdf

Minutes from the 2015 meeting in Dresden, Germany were reviewed and accepted without changes.

# 4 Review of TC-4 Charter and Membership Criteria

Mr. Kraemer read the TC-4 Charter and described the purpose of the TC. He also reviewed the requirements for TC membership:

- Attend one (1) meeting of the TC every two (2) years, or comparable participation.
- Review assigned papers in support of the yearly EMC Symposium(s).

The current TC-4 membership list is attached (Appendix B). It includes attendance information with respect to past TC-4 meeting, to include the August 19, 2015 meeting. It also notes which members are willing to review papers for the next EMC Symposium

Two questions were asked inquiring if TC4 was the correct place for discussion:

- 1) Is TC4 the correct committee to handle PCB design?
  - Due to the large scope of PCB design it would overlap with TC10, the specific scope of the work would determine which TC would be appropriate.





- 2) Does TC4 deal with wire coupling?
  - It is determined that if the discussion was based on the model or analysis of wire coupling then it would fall under the range of TC4.
  - If the discussion is based around signal integrity then it would fall under the TC10 category.

## 5 Review of the Committee Membership

The current officers are:

Chairman: John KraemerVice-Chairman: Ross Carlton

• Secretary: William Wantz

Committee members who are willing to review papers are requested to provide an updated resume to aid in distributing papers for review.

#### 6 Review of the Committee Website

Mr., John Kraemer reviewed the status of the TC-4 web site. The web has been updated since the last meeting. It includes the draft minutes from the Dresden meeting in 2016 as well as the agenda.

**ACTION:** TC-4 secretary will continue to update the TC-4 web site. [In Process]

#### 7 TAC Performance Guidelines for Technical Committees

TC-4 performance scores were in good standing according to the TAC meeting on 7/25/2016. The TC continues to score well due to the number of technical papers reviewed and the acceptance of TC-sponsored workshops and tutorials.

# 8 Program of Work Discussion

Current works

- P2716 Guide for the Characterization of the Effectiveness of Printed Circuit Board Level Shielding
  - o Headed by Mr. Davy Pissoort
- P2715 Guide for the Characterization of the Shielding Effectiveness of Planar Materials
  - o Headed by Mr. Alpesh Bhobe
- P1302 Guide for the Electromagnetic Characterization of Conductive Gaskets in the Frequency Range of DC to 40 GHz
  - o Headed by Mr. Davy Pissoort





- P2710 Electromagnetic Shielding Performance of Enclosures for Portable Electronic Devices
  - Headed by Mr. Alistair Duffy
- P299.1- IEEE Draft Standard Method for Measuring the Shielding Effectiveness of Enclosures and Boxes Having All Dimensions between 0.1 m and 2 m
  - o Finished in 2014

## 9 Subcommittee Update

- 9.1 SC1: Grounding and Bonding ~ closed in 2015
- 9.2 SC2: Gaskets

Absorbed into the IEEE-STD 1302-2008 revision group in 2015

#### 9.3 SC3: Materials

Mr. Mark Montrose, the chair of this committee, gave an update on the recent activities.

- Mr. Mark Montrose lead a workshop in Santa Clara, Ca in May of 2015
- A workshop was proposed for Dresden in August of 2015 but was not accepted
  - o The scope of the workshop was worked into the debugging workshop in Dresden

## 10 Summary of 2016 Symposium Activities (Chair)

Mr. Kraemer reviewed the TC's activities in support of the 2016 IEEE EMC Symposium in Ottawa. The TC plans to support the Symposium in the following ways:

- Reviewed 28 technical papers, 17 were accepted
  - o 7 accepted first round, 7 were rejected
  - o 14 needed second review
  - o 10 accepted papers and 4 rejected
  - o 61% acceptance rate
- Held annual meeting.
- Chaired 4 Technical Sessions

# 11 Plans for 2016 Symposium in Washington DC

Mr. Kraemer reviewed the TC's activities in support of the 2017 IEEE EMC Symposium in Washington DC. The TC plans to support the Symposium in the following ways:

- Review papers.
- Hold annual meeting.
- Chair Technical Sessions.
- Sponsor at least one Session, Workshop or Tutorial. Suggested activities were as follows:





- o A workshop organized by Mr. Montrose on the topic of "Properties of Materials."
  - The workshop will consist of about 4 speakers with a 20-30 minute discussion followed by open session
  - Topics covered by this workshop should include
    - P.C.B. materials and their properties
    - Absorbers
    - Conductive plastics
    - Buried capacitance in materials
  - **ACTION ITEM** Write proposal for the workshop, with speakers due by Jan 1, 2017 (Mr. Mark Montrose)
- o "Filter Design" tutorial lead by Mr. John Kraemer
  - Topics covered by this tutorial should include
    - How they Work
    - Material Selection
    - Transient condition
    - Effects of a filter on stability
    - Use of a filter with audio frequency susceptibility
    - Trouble shooting
  - **ACTION ITEM** Write proposal for the workshop, with speakers due by Jan 1, 2017 (Mr. John Kraemer)
- o A workshop on the topic of "System Design"
  - Topics covered by this workshop should include
    - Interactions between components
  - **ACTION ITEM** Write proposal for the workshop, with speakers due by Jan 1, 2017 (Mr. Huadong Li)

## 12 Election of Officers, if needed

The TC4 officers have been in their position less than the two year rotation time and none needed to excuse themselves from the position. No new election is needed.

#### 13 New business

No new business was suggested to discuss.

## **Closing**

Meeting was adjourned at 1315

Minutes submitted by: William Wantz, Secretary, TC-4 (William@Spira-emi.com)





# APPENDIX A July 27, 2016 TC4 Meeting Attendance

NAME	AFFILITATION	EMAIL	WILLING TO REVIEW PAPERS?	TC-4 MTG ATTENDANCE (NOTE 2)	JULY 27, 2016 ATTENDANCE	MEMBER OF OBSERVER
Archambeault, Bruce	IBM	bruce.arch@ieee.org	(NOTE 1) Yes*	12, 15S	1	
Brull, Christian	Schlegel	christian.brull@schlegelemi.com	No	13, 14, 15S, 15D	1	11
Berger, Phil	Harman/Becker Automotive	bergerphi@mst.edu		12, 13, 14	1	М.
Burnham, Karen	Ford Motor Company	karen.burnham@gmail.com	Yes*	13, 15S	ac v	4.1
Carlton, Ross	National Instruments	ross.carlton@ieee.org	Yes	12,13, 14, 15S, 15D	Chris	M
Crowder, Michael	IBM	michaelc@us.ibm.com		13, 14		Н
Davis, Bob	Lockhhed Martin	robert.h.davis@lmco.com	Yes*	12, 15S		
Demharter, Robert	Wurth Electronik	Robert.Demharter@we-online.de	No			
Faraji, Parisa	Graftech Int'l	parisa.faraji@graftech.com		15D		
	Laird Technologies	gary.fenical@lairdtech.com	No	12, 13, 14		
enical, Gary	ARC Technologies	dgreen@arc-tech.com		12, 13, 14, 15S, 15D		
irren, David	Clemson University	hubing@clemson.edu	Yes*	14		
odd Hubing	Chomerics	dinman@parker.com	No	14, 15S, 15D		
man David	Onomeneo			13, 14, 15D	Del.	M
	TC-4\TC4 Membership List for 27JUL20		WILLING TO REVIEW	Ily 2016  TC-4 MTG ATTENDANCE	JULY 27, 2016	MEMBER OF
	TC-4\TC4 Membership List for 27JUL20	o16 mtg.doc 1 of 1	WILLING TO REVIEW PAPERS?			
Kraemer:\\\IEEE	AFFILITATION		WILLING TO REVIEW	TC-4 MTG ATTENDANCE	JULY 27, 2016	MEMBER OR
Kraemer:\\\IEEE	AFFILITATION  Dayton T. Brown	EMAIL	WILLING TO REVIEW PAPERS?	TC-4 MTG ATTENDANCE (NOTE 2)	JULY 27, 2016	MEMBER OR
Kraemer:\\\JEEE  NAME  Kerns, Donald	AFFILITATION  Dayton T. Brown	EMAIL drkems@ieee.org	WILLING TO REVIEW PAPERS? (NOTE 1)	TC-4 MTG ATTENDANCE (NOTE 2)	JULY 27, 2016	MEMBER OR
Kraemer:\\\\EEE  NAME  Kerns, Donald  Kraemer, John	AFFILITATION  Dayton T. Brown  Rockwell Collins	EMAIL drkerns@ieee.org jgkraeme@rockwellcollins.com	WILLING TO REVIEW PAPERS? (NOTE 1)	TC-4 MTG ATTENDANCE (NOTE 2) 12, 14	JULY 27, 2016	MEMBER OR OBSERVER
NAME  NAME  Kerns, Donald  Kraemer, John  Kunkel, George	AFFILITATION  Dayton T. Brown  Rockwell Collins  Spira	EMAIL drkerns@ieee.org jgkraeme@rockwellcollins.com george@spira-emi.com	WILLING TO REVIEW PAPERS? (NOTE 1)	12, 14 12, 13, 14, 15S, 15D	JULY 27, 2016	MEMBER OR OBSERVER
Kraemer:\\\\IEEE  NAME  Kerns, Donald  Kraemer, John  Kunkel, George  arrabee, David	AFFILITATION  Dayton T. Brown  Rockwell Collins  Spira  NIST	EMAIL  drkerns@ieee.org jgkraeme@rockwellcollins.com george@spira-emi.com  david_a_larrabee@yahoo.com	WILLING TO REVIEW PAPERS? (NOTE 1)	TC-4 MTG ATTENDANCE (NOTE 2) 12, 14 12, 13, 14, 15S, 15D 12, 13, 15S	JULY 27, 2016	MEMBER OR OBSERVER
Kraemer:\\\\IEEE  NAME  Kerns, Donald  Kraemer, John  Kunkel, George  arrabee, David	AFFILITATION  Dayton T. Brown  Rockwell Collins  Spira  NIST  Graftech Int'I	EMAIL  drkerns@ieee.org  jgkraeme@rockwellcollins.com  george@spira-emi.com  david_a_larrabee@yahoo.com  lan.mccallum@graftech.com	WILLING TO REVIEW PAPERS? (NOTE 1)  Yes*  Yes*	12, 14  12, 13, 14, 15S, 15D  12, 13, 15S  15S*	JULY 27, 2016	MEMBER OR OBSERVER
Kraemer:\\\\IEEE  NAME  Kerns, Donald  Kraemer, John  Kunkel, George  arrabee, David  toCallum, Ian  Icinerney, Mike	AFFILITATION  Dayton T. Brown  Rockwell Collins  Spira  NIST  Graftech Int'I	EMAIL  drkems@ieee.org jgkraeme@rockwellcollins.com george@spira-emi.com  david_a_larrabee@yahoo.com  lan.mccallum@graftech.com  mkmcinerney@ieee.org	WILLING TO REVIEW PAPERS? (NOTE 1)	TC-4 MTG ATTENDANCE (NOTE 2) 12, 14 12, 13, 14, 15S, 15D 12, 13, 15S 15S* 14	JULY 27, 2016 ATTENDANCE	MEMBER OR OBSERVER
Kraemer:\\JEEE  NAME  Kerns, Donald  Kraemer, John  Kunkel, George  arrabee, David  tcCallum, Ian  lcInerney, Mike	AFFILITATION  Dayton T. Brown  Rockwell Collins  Spira  NIST  Graftech Int'I  IEEE  Oracle  Montrose Compliance	EMAIL  drkerns@ieee.org  jgkraeme@rockwellcollins.com  george@spira-emi.com  david a larrabee@yahoo.com  lan.mccallum@graftech.com  mkmcinerney@ieee.org  monrad.monsen@oracle.com	WILLING TO REVIEW PAPERS? (NOTE 1)  Yes*  Yes*	12, 14 12, 13, 14, 15S, 15D 12, 13, 15S 15S* 14 15S, 15S 12, 13, 14, 15S	JULY 27, 2016	MEMBER OR OBSERVER
Kraemer:\\JEEE  NAME  Kerns, Donald  Kraemer, John  Kunkel, George  arrabee, David  dcCallum, Ian  dcInerney, Mike  donsen, Monrad  controse, Mark	AFFILITATION  Dayton T. Brown  Rockwell Collins  Spira  NIST  Graftech Int'I  IEEE  Oracle  Montrose Compliance  Alion	EMAIL  drkerns@ieee.org  jgkraeme@rockwellcollins.com  george@spira-emi.com  david_a_larrabee@yahoo.com  lan.mccallum@graftech.com  mkmcinerney@ieee.org  monrad.monsen@oracle.com  m.montrose@ieee.org	WILLING TO REVIEW PAPERS? (NOTE 1)  Yes*  Yes*  Yes*	12, 14  12, 13, 14, 15S, 15D  12, 13, 15S  15S*  14  15S,  15S  12, 13, 14, 15S	JULY 27, 2016 ATTENDANCE	MEMBER OR OBSERVER
Kraemer:\\\\IEEE  NAME  Kerns, Donald  Kraemer, John  Kunkel, George  arrabee, David  tcCallum, Ian  Icinerney, Mike  Iconsen, Monrad  controse, Mark  Connor, Finili  ssoort, Davy	AFFILITATION  Dayton T. Brown  Rockwell Collins  Spira  NIST  Graftech Int'I  IEEE  Oracle  Montrose Compliance  Alion  KU Leuven	EMAIL  drkerns@ieee.org  igkraeme@rockwellcollins.com  george@spira-emi.com  david_a_larrabee@yahoo.com  lan.mccallum@graftech.com  mkmcinerney@ieee.org  monrad.monsen@oracle.com  m.montrose@ieee.org  foconnor@alionscience.com	WILLING TO REVIEW PAPERS? (NOTE 1)  Yes*  Yes*  Yes*  Yes*	12, 14 12, 13, 14, 15S, 15D 12, 13, 15S 15S* 14 15S, 15S 12, 13, 14, 15S 12, 13, 15S 13, 14, 15S, 15D	JULY 27, 2016 ATTENDANCE  W  M  M  M  M  M  M  M  M  M  M  M  M	MEMBER OR OBSERVER
Kraemer:\\JEEE  NAME  Kerns, Donald  Kraemer, John  Kunkel, George  arrabee, David  dcCallum, Ian  lcInerney, Mike  lonsen, Monrad  controse, Mark  Connor, Finil	AFFILITATION  Dayton T. Brown  Rockwell Collins  Spira  NIST  Graftech Int'l  IEEE  Oracle  Montrose Compliance  Alion  KU Leuven  TU Eindhoven	EMAIL  drkems@ieee.org  jgkraeme@rockwellcollins.com  george@spira-emi.com  david_a_larrabee@yahoo.com  lan.mccallum@graftech.com  mkmcinerney@ieee.org  monrad.monsen@oracle.com  m.montrose@ieee.org  foconnor@alionscience.com  davy.pissoort@kuleuven.be	WILLING TO REVIEW PAPERS? (NOTE 1)  Yes*  Yes*  Yes*  Yes*  Yes*	12, 14  12, 13, 14, 15S, 15D  12, 13, 15S  15S*  14  15S,  15S  12, 13, 14, 15S  12, 13, 14, 15S  12, 13, 14, 15S	JULY 27, 2016 ATTENDANCE  W  M  M  M  M  M  M  M  M  M  M  M  M	MEMBER OR OBSERVER  M M M
Kraemer:\\JEEE  NAME  Kerns, Donald  Kraemer, John  Kunkel, George  arrabee, David  tcCallum, Ian  lcInerney, Mike  tonsen, Monrad  ontrose, Mark  Connor, Fin	AFFILITATION  Dayton T. Brown  Rockwell Collins  Spira  NIST  Graftech Int'I  IEEE  Oracle  Montrose Compliance  Alion  KU Leuven  TU Eindhoven	EMAIL  drkerns@ieee.org  jgkraeme@rockwellcollins.com  george@spira-emi.com  david_a_larrabee@yahoo.com  lan.mccallum@graftech.com  mkmcinerney@ieee.org  monrad.monsen@oracle.com  m.montrose@ieee.org  foconnor@alionscience.com  davv.pissoort@kuleuven.be  a.Roch@tue.nl	WILLING TO REVIEW PAPERS? (NOTE 1)  Yes*  Yes*  Yes*  Yes*  Yes*  Yes*  Yes*	TC-4 MTG ATTENDANCE (NOTE 2)  12, 14  12, 13, 14, 15S, 15D  12, 13, 15S  15S*  14  15S,  15S  12, 13, 14, 15S  12, 13, 14, 15S  12, 13, 14, 15S  13, 14, 15S, 15D  15D	JULY 27, 2016 ATTENDANCE  W  M  M  M  M  M  M  M  M  M  M  M  M	MEMBER OR OBSERVER  M M M
Kraemer:\\JEEE  NAME  Kerns, Donald  Kraemer, John  Kunkel, George  arrabee, David  dcCallum, Ian  lcInerney, Mike  lonsen, Monrad  controse, Mark  Connor, Finil	AFFILITATION  Dayton T. Brown  Rockwell Collins  Spira  NIST  Graftech Int'I  IEEE  Oracle  Montrose Compliance  Alion  KU Leuven  TU Eindhoven  NASA  Laird Technologies	EMAIL  drkerns@ieee.org  jgkraeme@rockwellcollins.com  george@spira-emi.com  david_a_larrabee@yahoo.com  lan.mccallum@graftech.com  mkmcinerney@ieee.org  monrad.monsen@oracle.com  m.montrose@ieee.org  foconnor@alionscience.com  davy.pissoort@kuleuven.be a.Roch@tue.nl	WILLING TO REVIEW PAPERS? (NOTE 1)  Yes*  Yes*  Yes*  Yes*  Yes*  Yes*  Yes*	12, 14  12, 13, 14, 15S, 15D  12, 13, 15S  15S*  14  15S,  15S  12, 13, 14, 15S  12, 13, 14, 15S  12, 13, 14, 15S	JULY 27, 2016 ATTENDANCE  W  M  M  M  M  M  M  M  M  M  M  M  M	MEMBER OR OBSERVER  M M M





NAME	AFFILITATION	EMAIL	WILLING TO REVIEW PAPERS? (NOTE 1)	TC-4 MTG ATTENDANCE (NOTE 2)	JULY 27, 2016 ATTENDANCE	MEMBER OR OBSERVER
Wantz, William (Will)	Spira Mfg	William@Spira-emi.com	No	15S, 15D	V	M
Wegrzyniak, Pawel	Laird Technologies	Pawel.wegrzyniak@lairdtech,com		14		
Williams, Kimball	IEEE	k.williams@ieee.org		14		
Zeng, Hua	Hitachi Automotive	hua.zeng@hitachi-automotive.us	Yes	12, 15S		
EdHare	ARRI	warfi @arrl.org	Yes	_	V	O, but
PATIK STEPANIA	N 176 ELECT	THE RAPIKS DITG-BESTERNIC	cs. Com	_		MIMBO
aul Rosensteel	N ITG EXECT Manteck International 2 U.S. Coast Guard	Paul. rosensteel @ mantech. com				OBSERVER
SHAFII, JAMA	- UTC Aerospale Systems	jamaloshafii @utas. utc.	com Yes		/	member
tuadong Li	Milex	huadong limsky com	Ves			membe &
SHANEH, ALL	JPL	ALI-R. GHANEHOUPL, NASA. 6	ev		1	Menbeg
lille OLiver	MAJR Products Cosp.	emi @majr.com	Yes		V	member
ntis Semanson	R.F.A	(Semanso@gmaile	, 4			
		-0				
	MA SALA					
TES: * indicates member of 15S indicates Santa	completed round 1 and round Clara TC-4 meeting, 15D for	2 reviews for Ottawa Sympossium. Dresden meeting attendance.		-		
	4\TC4 Membership List for 27JUL20:	16 mte.doc 3 of 1		y 2016		





### APPENDIX B

TC4 Membership List 20 AUGUST 2015

NAME	AFFILITATION	EMAIL	WILLING TO REVIEW PAPERS? (NOTE 1)	TC-4 MTG ATTENDANCE (NOTE 2)
Archambeault, Bruce	IBM	barch@us.ibm.com	Yes	12, 15S
Berger, Phil	Missouri University of Science & Technology	bergerphi@mst.edu	Yes	12, 13, 14
Brull, Christian	Schlegel	christian.brull@schlegelemi.com	No	13, 14, 15S, 15D, 16
Burnham, Karen	Northrop Grumman	karen.burnham@gmail.com	Yes	13, 15S, 16
Carlton, Ross	National Instruments	ross.carlton@ieee.org	Yes	12,13, 14, 15S, 15D, 16
Crowder, Michael	IBM	michaelc@us.ibm.com		13, 14
Davis, Bob	Lockhhed Martin	robert.h.davis@Imco.com	Yes	12, 15S
Demharter, Robert	Wurth Electronik	Robert.Demharter@we-online.de	No	15D
Faraji, Parisa	Graftech Int'l	parisa.faraji@graftech.com		12, 13, 14
Fenical, Gary	Laird Technologies	gary.fenical@lairdtech.com	No	12, 13, 14, 15S, 15D
Ghaneh, Ali	JPL	Ali.R.Ghaneh@JPL.NASA.gov		16
Grren, David	ARC Technologies	dgreen@arc-tech.com		14
Todd Hubing	Clemson University	hubing@clemson.edu	Yes	14, 15S, 15D
Inman, David	Chomerics	dinman@parker.com	No	13, 14, 15D,16
Kerns, Donald	Dayton T. Brown	drkerns@ieee.org		12, 14
Kimmel, William	Kimmel-Gerke Assoc.	bkimmel@emiguru.com		14
Kraemer, John	Rockwell Collins	igkraeme@rockwellcollins.com	Yes	12, 13, 14, 15S, 15D, 16
Kunkel, George	Spira	george@spira-emi.com		12, 13, 15S, 16
Larrabee, David	NIST	david_a_larrabee@yahoo.com	Yes	15S
Li, Huadong	Molex	Huadong.Li@Molex.com	Yes	16
McCallum, Ian	Graftech Int'l	lan.mccallum@graftech.com		14
McInerney, Mike	IEEE	mkmcinerney@ieee.org	Yes	15S,
Monsen, Monrad	Oracle	monrad.monsen@oracle.com		15S, 16
Montrose, Mark	Montrose Compliance	m.montrose@ieee.org		12, 13, 14, 15S, 16
O'Connor, Fin	Alion	foconnor@alionscience.com	Yes	12, 13, 15S, 16
Oliver, Mike	MAJR Products Corp.	EMI@MAJR.com	Yes	16
Pissoort, Davy	KU Leuven	davy.pissoort@kulueven.be	Yes	13, 14, 15S, 15D, 16
Roch, Anne	TU Eindhoven	a.Roch@tve.nl	Yes	15D
Scully, Bob	NASA	robert.c.scully@nasa.gov	Yes	15S
Shafii, Jamal	UTC Aerospace Sys.	Jamal.Shafii@utas.utc.com	Yes	16
She, Brian	Laird Technologies	brian.she@lairdtech.com		12, 13, 14
Steffka, Mark	General Motors	msteffka@ieee.org		15S





NAME	AFFILITATION	EMAIL	WILLING TO REVIEW PAPERS? (NOTE 1)	TC-4 MTG ATTENDANCE (NOTE 2)
Stepanian, Rafik	ITG Electronics	RafikS@ITG-Electronics.com		16
Tazi, Aziz	Transport Canada	Aziz.tazi@tc.gc.ca		14
Wantz, William (Will)	Spira Mfg	William@Spira-emi.com	No	13, 14, 15S, 15D, 16
Wegrzyniak, Pawel	Laird Technologies	Pawel.wegrzyniak@lairdtech,com		14
Williams, Kimball	IEEE	k.williams@ieee.org		14
Zeng, Hua	Hitachi Automotive	hua.zeng@hitachi-automotive.us	Yes	12, 15S

#### NOTES:

- \* indicates member reviewed papers for Ottawa Symposium.
   15S indicates Santa Clara TC-4 meeting, 15D for Dresden meeting attendance.